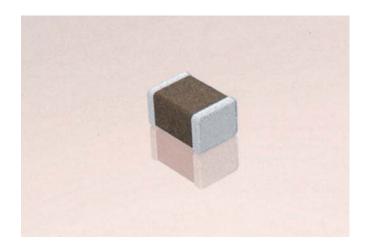
# **Y5V Dielectric**

### **General Specifications**

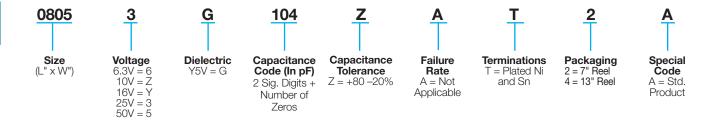


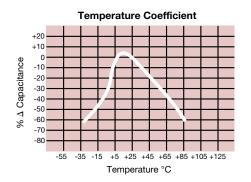


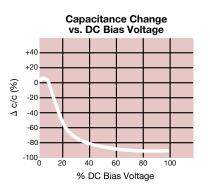
Y5V formulations are for general-purpose use in a limited temperature range. They have a wide temperature characteristic of +22% -82% capacitance change over the operating temperature range of  $-30^{\circ}$ C to  $+85^{\circ}$ C.

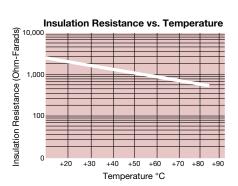
These characteristics make Y5V ideal for decoupling applications within limited temperature range.

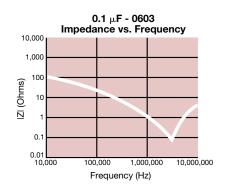
#### PART NUMBER (see page 2 for complete part number explanation)

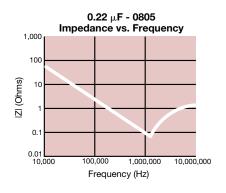


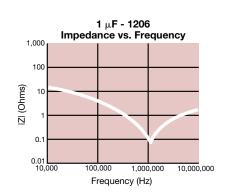












## **Y5V Dielectric**

## **Specifications and Test Methods**



Parame	ter/Test	Y5V Specification Limits	Measuring Conditions							
<b>Operating Tem</b>	perature Range	-30°C to +85°C	Temperature Cycle Chamber							
Capac		Within specified tolerance		<b>,</b>						
Dissipatio	on Factor	≤ 5.0% for ≥ 50V DC rating ≤ 7.0% for 25V DC rating ≤ 9.0% for 16V DC rating ≤ 12.5% for ≤ 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz							
Insulation I	Resistance	100,000MΩ or 500MΩ - μF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity							
Dielectric	Strength	No breakdown or visual defects	Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)							
	Appearance	No defects	Deflection: 2mm Test Time: 30 seconds							
Resistance to Flexure Stresses	Capacitance Variation	≤ ±30%								
	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	≥ Initial Value x 0.1	90 mm							
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at $230 \pm 5^{\circ}$ C for 5.0 ± 0.5 seconds							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance Variation	≤ ±20%	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for $24 \pm 2$ hours before measuring electrical properties.							
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	Meets Initial Values (As Above)								
	Dielectric Strength	Meets Initial Values (As Above)								
	Appearance	No visual defects	Step 1: -30°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±20%	Step 2: Room Temp	≤ 3 minutes						
Thermal	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes						
Shock	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ±2 hours at room temperature							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±30%	<ul> <li>Charge device with twice rated voltage in test chamber set at 85°C ± 2°C for 1000 hours (+48, -0)</li> <li>Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring.</li> </ul>							
Load Life	Dissipation Factor	≤ Initial Value x 1.5 (See Above)								
	Insulation Resistance	≥ Initial Value x 0.1 (See Above)								
	Dielectric Strength	Meets Initial Values (As Above)								
Load Humidity	Appearance	No visual defects	Store in a test shamh	$ar a t a t 85^{\circ}$						
	Capacitance Variation	≤ ±30%	<ul> <li>Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.</li> <li>Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.</li> </ul>							
	Dissipation Factor	≤ Initial Value x 1.5 (See above)								
	Insulation Resistance	≥ Initial Value x 0.1 (See Above)								
	Dielectric Strength	Meets Initial Values (As Above)								



## **Y5V Dielectric**



### **Capacitance Range**

#### **PREFERRED SIZES ARE SHADED**

				•																		
SIZE 0201		201	0402			0603			0805				1206				1210					
Soldering		Reflo	w Only		Reflow Only		Reflow Only			Reflow/Wave				Reflow/Wave				Reflow Only				
Packaging		All F	Paper		All Paper		All Paper			Paper/Embossed				Paper/Embossed				Paper/Embossed				
(L) Length	mm (in.)		± 0.03 ± 0.001)		1.00 ± 0.10 (0.040 ± 0.004)		1.60 ± 0.15 (0.063 ± 0.006)			2.01 ± 0.20 (0.079 ± 0.008)				3.20 ± 0.20 (0.126 ± 0.008)				3.20 ± 0.20 (0.126 ± 0.008)				
(W) Width	mm (in.)	(0.011	± 0.03 ± 0.001)		0.50 ± 0.10 (0.020 ± 0.004)			.81 ± 0.15 (0.032 ± 0.006)			1.25 ± 0.20 (0.049 ± 0.008)				1.60 ± 0.20 (0.063 ± 0.008)				2.50 ± 0.20 (0.098 ± 0.008)			
(t) Terminal	mm (in.)		± 0.05 ± 0.002)		0.25 ± 0.15 (0.010 ± 0.00	06)	0.35 ± 0.15 (0.014 ± 0.006)			0.50 ± 0.25 (0.020 ± 0.010)			0.50 ± 0.25 (0.020 ± 0.010)				.50 ± 0.25 (0.020 ± 0.010)					
	WVDC	6.3	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
Cap (pF)	820 1000 2200		A A															_			<u> </u>	 >
Cap (µF)	4700 0.010 0.022	A A	A A	С	C C	C C				G G									$\leq$		$\sum$	Î <u></u> ŢŢ
	0.047 0.10 0.22	A		C C				G	G G G	G			J N	K N				1		a t	1	1
	0.47 1.0 2.2						G	G G			N	K N N	N N			M	М	М				N
	4.7 10.0 22.0 47.0										N				QQ	P Q			Х	Q	N Q	
	WVDC	6.3	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
SIZE		0201		0402			0603			0805			•	1206				1210				
Letter	A			<b>E</b> 0.71	G	J	K		M	<b>N</b>		P		<b>Q</b>	2.29		Y		<b>Z</b> 79			
Max. Thickness	0.33 (0.013)			(0.028)	0.90 (0.035)	0.94 (0.037)	1.02 (0.040)		1.27 (0.050)		-	1.52 (0.060)		1.78 (0.070)			2.54	(0.1				
Thickness	(0.013)	PAPER					(0.040	) (0	.050)	(0.05	00)	· /	`	,	(0.09	0) (	0.100)	(0.1	10)			
	PAPER EMBOSSED																					